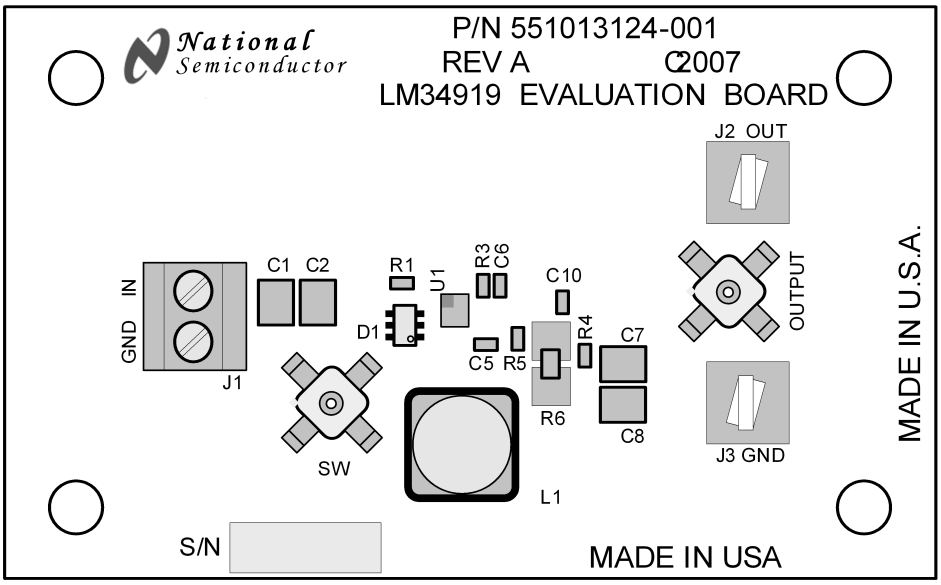
AN-1650 LM34919 Evaluation Board

1 Introduction

The LM34919EVAL evaluation board provides the design engineer with a fully functional buck regulator, employing the constant on-time (COT) operating principle. This evaluation board provides a 5V output over an input range of 8V to 40V. The circuit delivers load currents to 600 mA, with current limit set at a nominal 700 mA. The board is populated with all components except R5, C9 and C10. These components provide options for managing the output ripple as described later in this document.

The board's specification are:

- Input Voltage: 8V to 40V
- Output Voltage: 5V
- Maximum load current: 600 mA
- Minimum load current: 0A
- Current Limit: 640 mA to 730 mA
- Measured Efficiency: 92.7% (V_{IN} = 8V, I_{OUT} = 300 mA)
- Nominal Switching Frequency: 800 kHz
- Size: 2.6 in. x 1.6 in. x 0.5 in



Note: R2, C3, C4 and C9 are located on board's back side.

Figure 1. Evaluation Board - Top Side

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2 Theory of Operation

Refer to the evaluation board schematic in Figure 5, which contains a simplified block diagram of the LM34919. When the circuit is in regulation, the buck switch is on each cycle for a time determined by R1 and VIN according to the equation:

$$t_{ON} = \frac{1.13 \times 10^{-10} \times (R1 + 1.4\ k\Omega)}{V_{IN} - 1.5V} + 100\ ns \quad (1)$$

The on-time of this evaluation board ranges from ≅875 ns at VIN = 8V, to ≅231 ns at VIN = 40V. The on-time varies inversely with VIN to maintain a nearly constant switching frequency. At the end of each on-time the Minimum Off-Timer ensures the buck switch is off for at least 155 ns. In normal operation, the off-time is much longer. During the off-time, the load current is supplied by the output capacitor (C7, C8). When the output voltage falls sufficiently that the voltage at FB is below 2.5V, the regulation comparator initiates a new on-time period. For stable, fixed frequency operation, a minimum of 25 mV of ripple is required at FB to switch the regulation comparator. The current limit threshold, is ≅640 mA at Vin = 8V, and ≅730 mA at Vin = 40V. The variation is due to the change in ripple current amplitude as Vin varies. Refer to the LM34919 data sheet for a more detailed block diagram, and a complete description of the various functional blocks.

3 Board Layout and Probing

The pictorial in Figure 1 shows the placement of the circuit components. The following should be kept in mind when the board is powered:

1) When operating at high input voltage and high load current, forced air flow may be necessary.

2) The LM34919, and diode D1 may be hot to the touch when operating at high input voltage and high load current.

3) Use CAUTION when probing the circuit at high input voltages to prevent injury, as well as possible damage to the circuit.

4) At maximum load current (0.6A), the wire size and length used to connect the load becomes important. Ensure there is not a significant drop in the wires between this evaluation board and the load.

4 Board Connection/Start-up

The input connections are made to the J1 connector. The load is connected to the J2 (OUT) and J3 (GND) terminals. Ensure the wires are adequately sized for the intended load current. Before start-up a voltmeter should be connected to the input terminals, and to the output terminals. The load current should be monitored with an ammeter or a current probe. It is recommended that the input voltage be increased gradually to 8V, at which time the output voltage should be 5V. If the output voltage is correct with 8V at VIN, then increase the input voltage as desired and proceed with evaluating the circuit. DO NOT EXCEED 40V AT VIN.

5 Output Ripple Control

The LM34919 requires a minimum of 25 mVp-p ripple at the FB pin, in phase with the switching waveform at the SW pin, for proper operation. The required ripple can be supplied from ripple at V_{OUT}, through the feedback resistors as described in Options A and B below, or the ripple can be generated separately (using R5, C9, and C10) in order to keep the ripple at V_{OUT} at a minimum (Option C).

Option A) Lowest Cost Configuration: This evaluation board is supplied with R4 installed in series with the output capacitance (C7, C8). Since ≥25 mVp-p are required at the FB pin, R4 is chosen to generate ≥50 mVp-p at V_{OUT}, knowing that the minimum ripple current in this circuit is ≅155 mAp-p at minimum V_{IN}. Using 0.39Ω for R4, the ripple at V_{OUT} ranges from ≅60 mVp-p to ≅140 mVp-p over the input voltage range. If the application can accept this ripple level, this is the most economical solution. The circuit is shown in Figure 2 and Figure 8.

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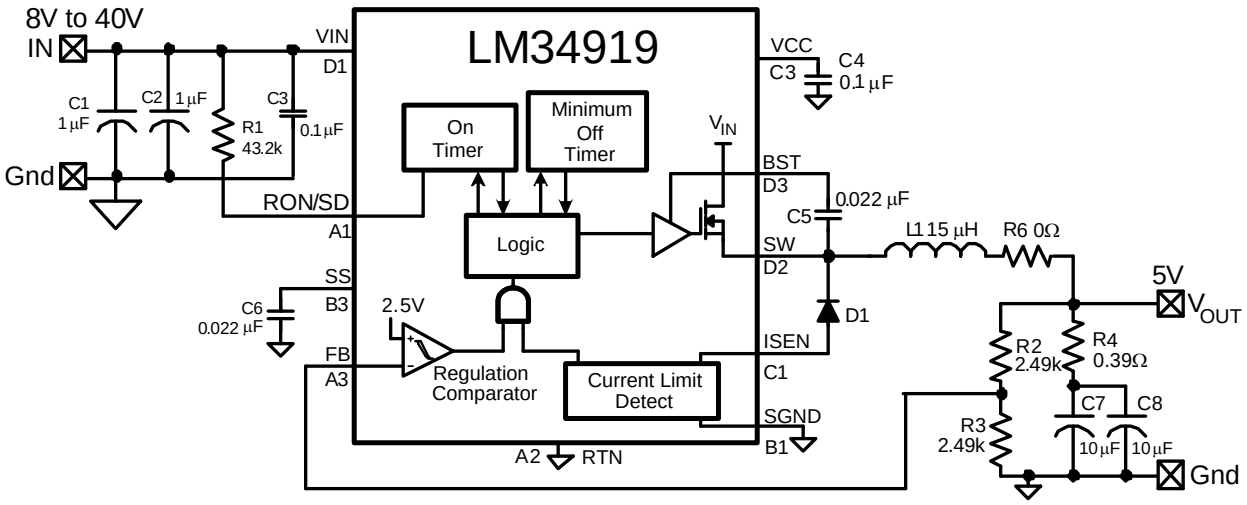


Figure 2. Lowest Cost Configuration

Option B) Intermediate Ripple Configuration: This configuration generates less ripple at V_{OUT} than option A above by the addition of one capacitor (Cff) across R2, as shown in Figure 3.

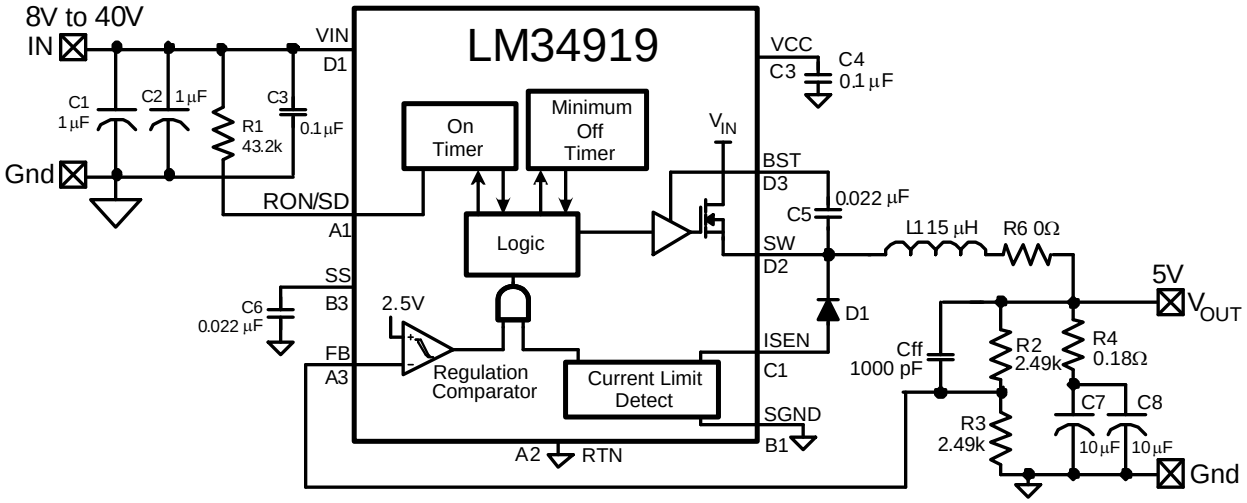


Figure 3. Intermediate Ripple Configuration

Since the output ripple is passed by Cff to the FB pin with little or no attenuation, R4 can be reduced so the minimum ripple at V_{OUT} is ≅25 mVp-p. The minimum value for Cff is calculated from:

$$Cff \geq \frac{t_{ON\ (max)}}{(R2//R3)} \tag{2}$$

where $t_{ON(max)}$ is the maximum on-time (at minimum V_{IN}), and R2//R3 is the parallel equivalent of the feedback resistors. See Figure 8.

Option C) Minimum Ripple Configuration: To obtain minimum ripple at V_{OUT}, R4 is set to 0Ω, and R5, C9, and C10 are added to generate the required ripple for the FB pin. In this configuration, the output ripple is determined primarily by the ESR of the output capacitance and the inductor's ripple current.

The ripple voltage required by the FB pin is generated by R5, C10, and C9 since the SW pin switches from -1V to V_{IN}, and the right end of C10 is a virtual ground. The values for R5 and C10 are chosen to generate a 50-100 mVp-p triangle waveform at their junction. That triangle wave is then coupled to the FB pin through C9. The following procedure is used to calculate values for R5, C10 and C9:

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1) Calculate the voltage V_A:

$$V_A = V_{OUT} - (V_{SW} \times (1 - (V_{OUT}/V_{IN}))) \quad (3)$$

where V_{SW} is the absolute value of the voltage at the SW pin during the off-time (typically 1V), and V_{IN} is the minimum input voltage. For this circuit, V_A calculates to 4.63V. This is the approximate DC voltage at the R5/C10 junction, and is used in the next equation.

2) Calculate the R5 x C10 product:

$$R5 \times C10 = \frac{(V_{IN} - V_A) \times t_{ON}}{\Delta V} \quad (4)$$

where t_{ON} is the maximum on-time (≅875 ns), V_{IN} is the minimum input voltage, and ΔV is the desired ripple amplitude at the R5/C10 junction, 100 mVp-p for this example.

$$R5 \times C10 = \frac{(8V - 4.63V) \times 875\ ns}{0.1V} = 29.5 \times 10^{-6} \quad (5)$$

R5 and C10 are then chosen from standard value components to satisfy the above product. Typically C10 is 3000 to 5000 pF, and R5 is 10kΩ to 300 kΩ. C9 is chosen large compared to C10, typically 0.1 µF. See Figure 4 and Figure 8.

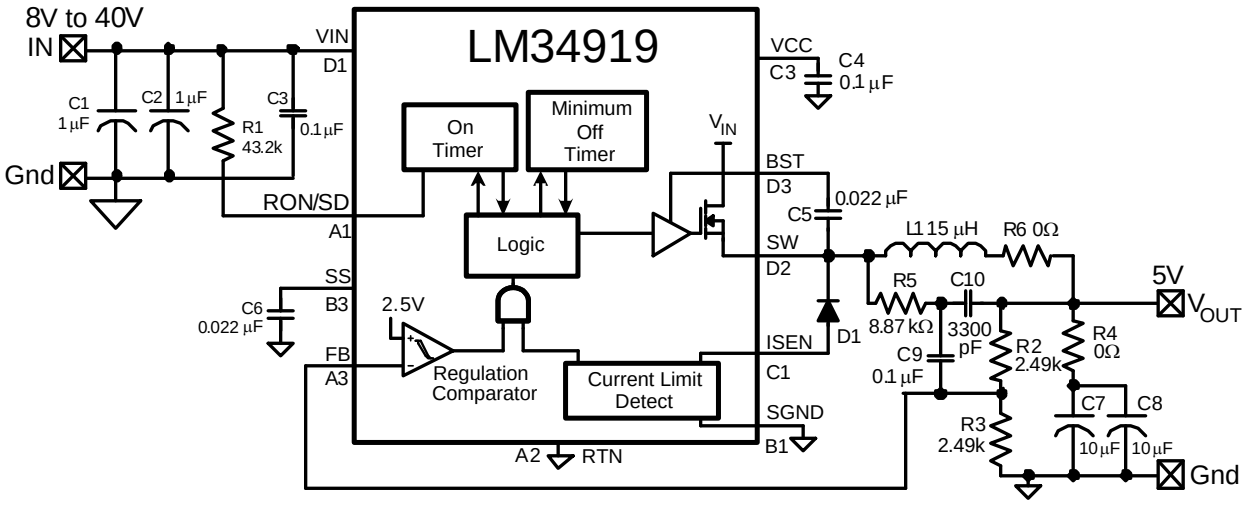


Figure 4. Minimum Output Ripple Configuration

6 Monitor The Inductor Current

The inductor's current can be monitored or viewed on a scope with a current probe. Remove R6, and install an appropriate current loop across the two large pads where R6 was located. In this way the inductor's ripple current and peak current can be accurately determined.

7 Scope Probe Adapters

Scope probe adapters are provided on this evaluation board for monitoring the waveform at the SW pin, and at the circuit's output (V_{OUT}), without using the probe's ground lead which can pick up noise from the switching waveforms. The probe adapters are suitable for Tektronix P6137 or similar probes, with a 0.135" diameter.

8 Minimum Load Current

The LM34919 requires a minimum load current of ≅1 mA to ensure the boost capacitor (C5) is recharged sufficiently during each off-time. In this evaluation board, the minimum load current is provided by the feedback resistors allowing the board's minimum load current at V_{OUT} to be specified at zero.

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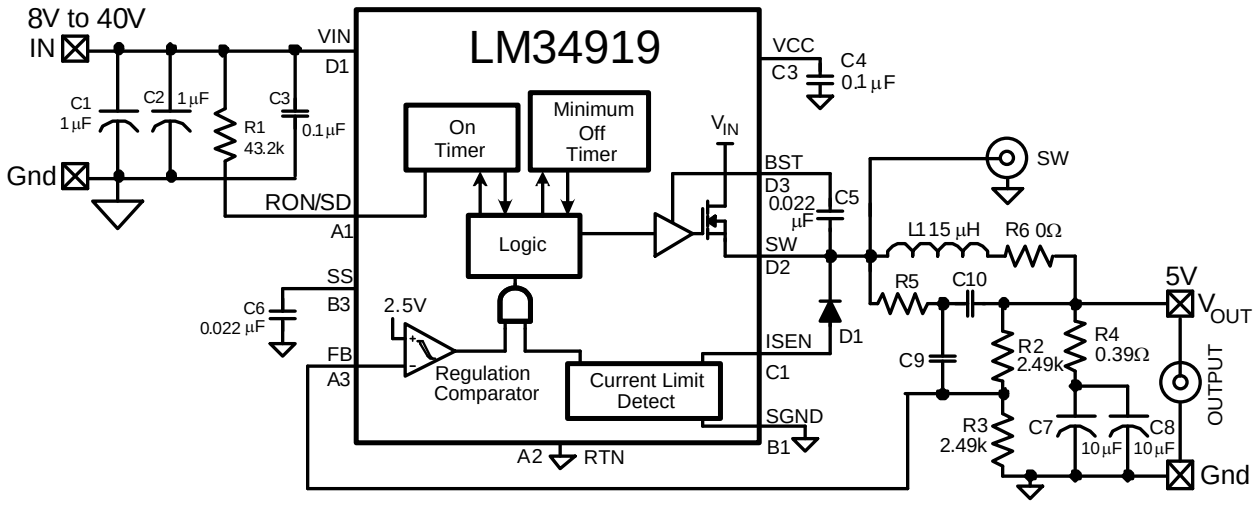


Figure 5. Complete Evaluation Board Schematic

Table 1. Bill of Materials

Item	Description	Mfg., Part Number	Package	Value
C1, C2	Ceramic Capacitor	TDK C3216X7R1H105M	1210	1.0 µF, 50V
C3	Ceramic Capacitor	TDK C1608X7R1H104K	0603	0.1 µF, 50V
C4	Ceramic Capacitor	TDK C1608X7R1H104K	0603	0.1 µF, 50V
C5, C6	Ceramic Capacitor	TDK C1608X7R1H223K	0603	0.022 µF, 50V
C7, C8	Ceramic Capacitor	TDK C3216X7R1C106K	1206	10 µF, 16V
C9	Ceramic Capacitor	Unpopulated	0603	
C10	Ceramic Capacitor	Unpopulated	0603	
D1	Schottky Diode	Zetex ZLLS2000	SOT23-6	40V, 2.2A
L1	Power Inductor	Bussman DR73-150	7.6 mm x 7.6 mm	15 µH, 1.8A
R1	Resistor	Vishay CRCW06034322F	0603	43.2 kΩ
R2, R3	Resistor	Vishay CRCW06032491F	0603	2.49 kΩ
R4	Resistor	Panasonic ERJ3RQFR39	0603	0.39Ω
R5	Resistor	Unpopulated	0603	
R6	Resistor	Vishay CRCW08050000Z	0805	0Ω Jumper
U1	Switching Regulator	LM34919	10 Bump DSBGA	

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9 Circuit Performance

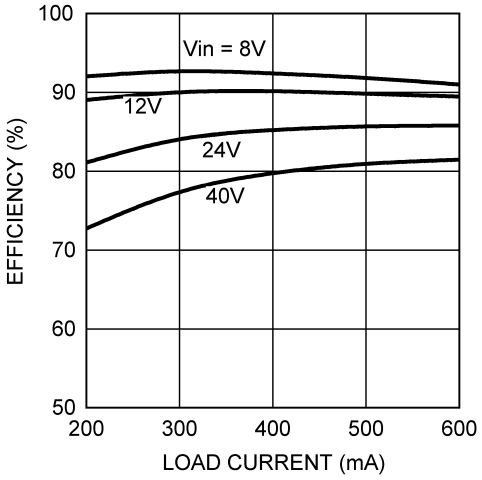


Figure 6. Efficiency vs Load Current

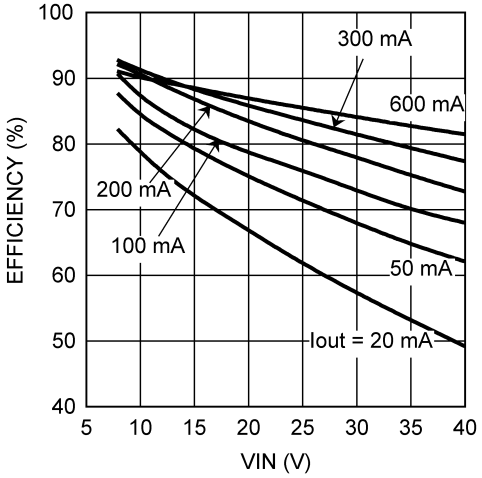


Figure 7. Efficiency vs Input Voltage

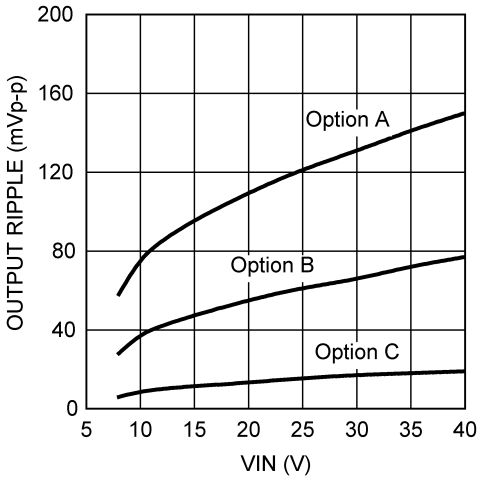


Figure 8. Output Voltage Ripple

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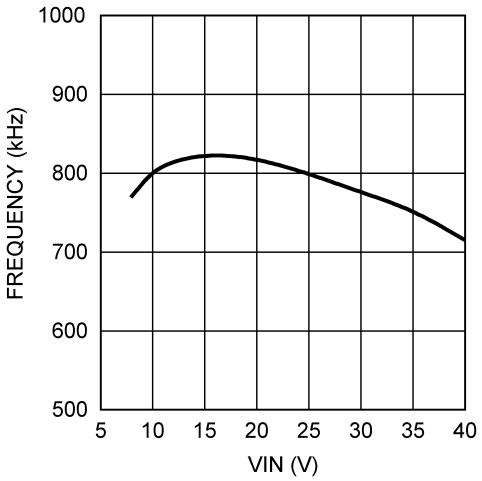


Figure 9. Switching Frequency vs. Input Voltage

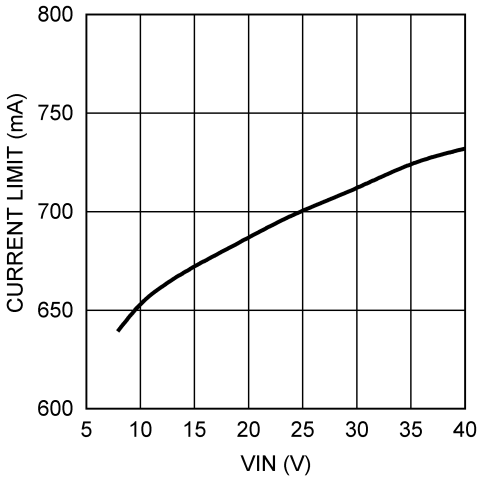
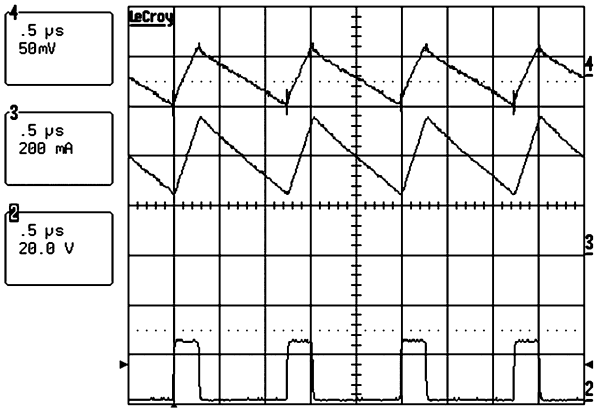


Figure 10. Load Current Limit vs Input Voltage

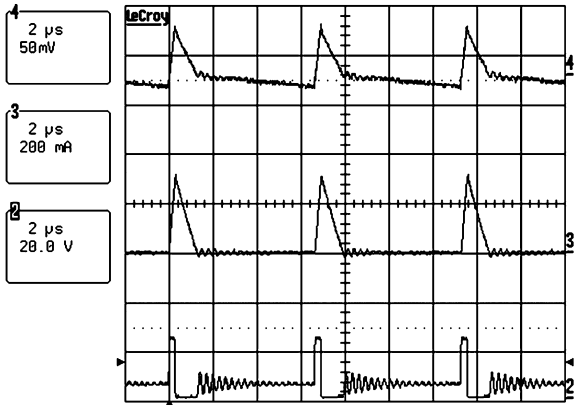
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10 Typical Waveforms



Trace 4 = V_{OUT}
Trace 3 = inductor Current
Trace 2 = SW Pin
Vin = 24V, Iout = 400 mA

Figure 11. Continuous Conduction Mode



Trace 4 = V_{OUT}
Trace 3 = inductor Current
Trace 2 = SW Pin
Vin = 24V, Iout = 20 mA

Figure 12. Discontinuous Conduction Mode

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11 PC Board Layout

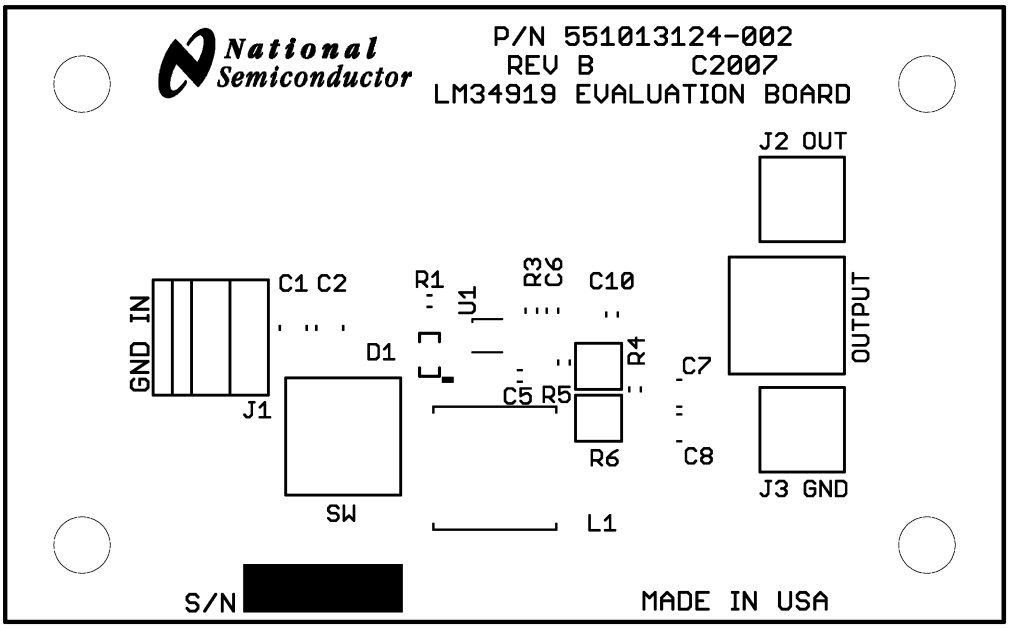


Figure 13. Board Silkscreen

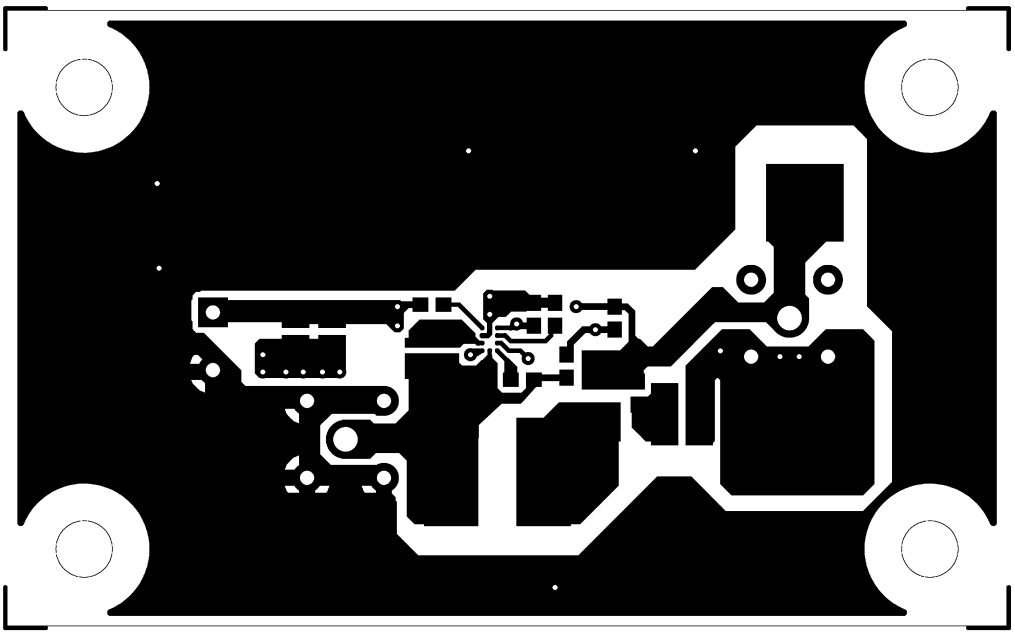


Figure 14. Board Top Layer

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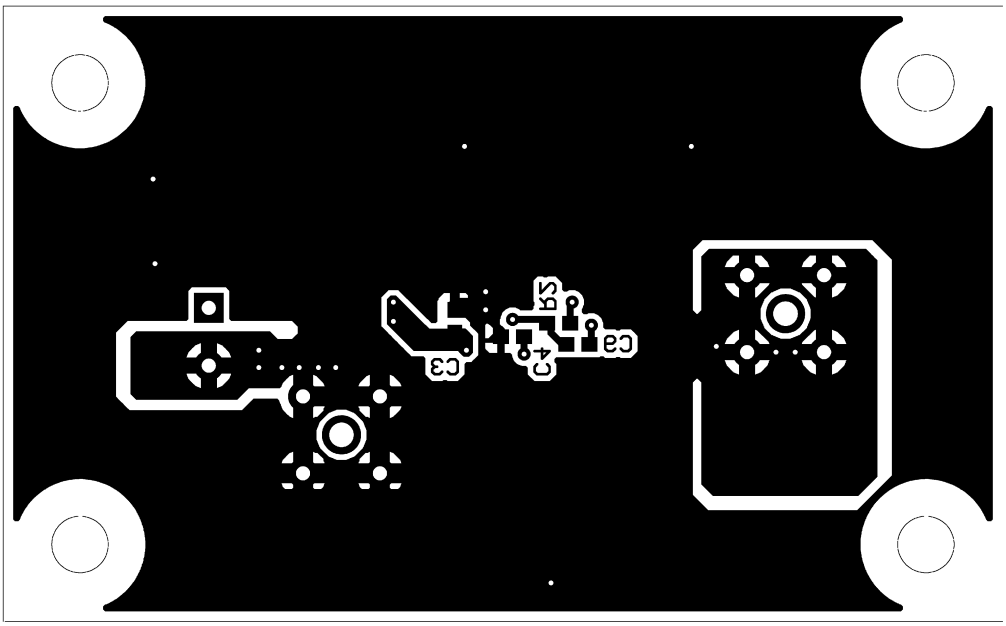


Figure 15. Board Second Layer (Viewed from Top)

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